

Manufacturer:

Epoxy Technology

Product Name:

Epo-Tek® OG116-31 Hybrid UV & Heat Cure Adhesive (3CC)

Manufacturer Part Number:

OG116-31-3CC

>> Find Out More Details on the Epo-Tek® OG116-31 Hybrid UV & Heat Cure Adhesive (3CC) <<

 Date:
 August 2021
 Rev: XII

 No. of Components:
 Single

 Mix Ratio by Weight:
 N/A

 Specific Gravity:
 1.20

 Pot Life:
 N/A

Shelf Life- Bulk: One year at room temperature
Shelf Life- Syringe: One year at room temperature

Recommended Cure	
Iron-Doped Mercury Flood Lamp 100 mW/cm ² @ 240-365 nm	> 30 sec.
Alternative Cures*	
Iron-Doped Mercury Spot Lamp	> 5 min.
365nm LED Flood Lamp	> 2.5 min.
Pulsed Mercury Lamp	> 60 sec.
UV Cure is complete after 24 hours from UV Exposure	
* Contact Technical Services for application- specific variations	

NOTES:

- Container(s) should be kept closed when not in use.
- Filled systems should be stirred thoroughly before mixing and prior to use.
- Performance properties (rheology, conductivity, others) of the Products may vary from those stated on the data sheet when bi-pak/syringe packaging or postprocessing of any kind is performed. Epoxy's warranties shall not apply to any products that have been reprocessed or repackaged from Epoxy's delivered status/container into any other containers of any kind, including but not limited to syringes, bi-paks, cartridges, pouches, tubes, capsules, films or other packages.

Product Description: EPO-TEK® OG116-31 is a single component, UV curable epoxy adhesive and encapsulant, designed for PCB and circuit assembly applications found in semiconductor, computer, medical, and scientific/OEM industries.

<u>Typical Properties:</u> Cure condition: Varies as required. *denotes test on lot acceptance basis Data below is not guaranteed. To be used as a guide only, not as a specification. Different batches, conditions & applications yield differing results.

PHYSICAL PROPERTIES: Cloudy White Color (before cure): Consistency: Viscous Liquid Viscosity (23°C) @ 10 rpm: 20,000-30,000 cPs Thixotropic Index: 1.3 **Glass Transition Temp:** ≥115 °C (Dynamic Cure:20-200°C/ISO 25 Min; Ramp -10-200°C @ 20°C/Min) Coefficient of Thermal Expansion (CTE): 41 x 10⁻⁶ in/in°C 170 x 10⁻⁶ in/in°C Below Tg: Above Tg: Shore D Hardness: Die Shear: **UV** Cure ≥10 Kg 3,556 UV Cure + 23°C/24 Hours 9,885.7 psi 27.8 Kg 27.1 Kg UV Cure + 80°C/1 Hour 9,636.8 psi **Degradation Temp:** 409 °C @ 200°C 0.30 % Weight Loss: @ 250°C 0.68 % @ 300°C 1.18 % **Suggested Operating Temperature:** < 300 °C (Intermittent) Storage Modulus: 263,581 psi Particle Size: ≤ 20 microns

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OPTICAL PROPERTIES @ 23°C:		
Spectral Transmission:	≥ 96% @ 660-1,640 nm	
	≥ 92% @ 500 nm	
Refractive Index (uncured):	1.5665 @ 589 nm	
Refractive Index (cured):	1.5842 @ 589 nm	

This information is based on data and tests believed to be accurate. Epoxy Technology, Inc. makes no warranties (expressed or implied) as to its accuracy and assumes no liability in connection with any use of this product.

Contact the professionals at Fiber Optic Center for a quote or to get more details.



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EPO-TEK® OG116-31 Advantages & Suggested Application Notes:

- Viscosity/rheology adapted to high volume syringe needle dispensing with no tailing.
- Versatility in cure. Product responds to a broad range of UV light, and secondary thermal post-curing.
- Suggested applications:
- Semiconductor: COB glob top covering IC's and wire bonds; glob top dam; encapsulating and sealing; adhesion to FR4, Kapton, silicon.
- Fiber Optic: making fiber optic pigtails; active alignment of optics; adhesion to many types of glass, metals, ceramics and plastics.
- ♦ Opto-electronic:
 - Perimeter/main seal for LCD's, compatible with VAN liquid crystal for LCoS devices.
 - Adhesive technology described in Technical Paper # 55 http://www.epotek.com/technical-papers.asp
- High Tg and low outgassing are indicative of its high temperature performance.

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